

LTM8056 121LD-BGA-PBF 15mm X 15mm X 4.92mm (TABLE OF MATERIAL DECLARATION)

The LTM8056 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2509	Barium Compounds	7727-43-7	0.00637	2.54
				Bismaleimide/Triazine/Resin/Filler Substance(Silica Crystalline)	105391-33-1,1156-51-0/9003-36-5/21645-51-2	0.04827	19.24
				Copper Metal	7440-50-8	0.14116	56.26
				Copper Compounds	147-14-8	0.00006	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00003	0.01
				Gold metal or alloy	7440-57-5	0.00048	0.19
				Nickel	7440-02-0	0.00221	0.88
				Zinc	7440-66-6	0.00028	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.03791	15.11
				Acrylic Resin	non-disclosure	0.01214	4.84
				Epoxy Resin	non-disclosure	0.00004	0.02
				Chromium(III) Oxide	1308-38-9	0.00001	0.00
				Silica amorphous	7631-86-9	0.00013	0.05
				Talc;not containing fibers like asbestos	14807-96-9	0.00073	0.29
				Aromatic Carbonyl compounds	non-disclosure	0.00070	0.28
				Cyanoguanidine	461-58-5	0.00002	0.01
				Calcium caobonate	471-34-1	0.00001	0.00
				Amine compounds	non-disclosure	0.00009	0.04
				Leveling agent and others	non-disclosure	0.00028	0.11
2	Solder Paste	Alloy	0.0455	Sn	7440-31-5	0.04323	95.00
				Sb	7440-36-0	0.00228	5.00
3	Passive/Active Components		0.8274	Iron Powder (Fe)	7439-89-6	0.63474	76.71
				Copper (Cu)	7440-50-8	0.16136	19.50
				Nickel (Ni)	7440-02-0	0.00381	0.46
				Tin (Sn)	7440-31-5	0.00576	0.70
				Ceramic (Ba) Compounds	12047-27-7	0.02173	2.63
4	Active Ics	Silicon	0.0175	Silicon	7440-21-3	0.01750	100.00
5	Wire	Gold	0.0003	Au	7440-57-5	0.00030	99.99
6	Solder Ball	SAC305	0.2035	Sn	7440-31-5	0.19638	96.50
				Ag	7440-22-4	0.00611	3.00
				Cu	7440-50-8	0.00102	0.50
7	Encapsulation	Epoxy Resin	1.4421	Fused Silica	60676-86-0	1.11330	77.20
				Epoxy Resin	non-disclosure	0.12835	8.90
				Phenol Resin	non-disclosure	0.12835	8.90
				Crytalline Silica	14808-60-7	0.04326	3.00
				Carbon Black	1333-86-4	0.00721	0.50
				Metal Hydroxide	non-disclosure	0.02163	1.50
Total Package Weight			2.7872				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts